DIGI® WIRELESS CONNECTIVITY KIT

Provides a hands-on way to learn how to use XBee® RF modules for device connectivity and sensor networking

Starting with very simple examples, we provide step-by-step guidance in assembling the kit components to create reliable wireless communications, working control systems, and sensing networks with incredible battery life and robust security. The kit is designed for anyone getting started in the world of XBee: hardware/software engineers, product managers, educators, students and even young inventors.

All examples are explained in-depth and include videos showcasing wireless communication in action. Some examples also incorporate the XBee Java Library, which can be used to integrate XBees modules into Java-based devices and applications. Each example is designed to be easy for anyone to use, and those with some programming background should find it simple to extend the examples to additional applications or use-cases.

The Kit Includes:

- ✓ 2 XBee Grove Development Boards
- ✓ 2 XBee 802.15.4 Modules
- ✓ 2 Micro-USB Cables
- ✓ 2 XBee Stickers

PART NUMBER	DESCRIPTION
XKB2-AT-WWC	Wireless Connectivity Kit w/ XBee S1 802.15.4
XKB2-A2T-WWC	Wireless Connectivity Kit w/ XBee S2C 802.15.4

XBee 802.15.4 Modules Included in the Kit

XBee and XBee-PRO 802.15.4 modules are embedded solutions providing wireless connectivity to devices. These modules use the IEEE 802.15.4 networking protocol for fast point-to-multipoint or peer-to-peer networking. They are designed for high-throughput applications requiring low latency and predictable communication timing.

XBee 802.15.4 modules are ideal for low-power, low-cost applications. These modules are easy-to-use, share a common footprint, and are fully interoperable with other XBee products utilizing the same technology. Module users have the ability to substitute one XBee module for another with minimal development time and risk.

SPECIFICATIONS	XBee® S2C 802.15.4	XBee-PRO® S2C 802.15.4
PERFORMANCE		
TRANSCEIVER CHIPSET	Silicon Labs EM357 SoC	
DATA RATE	RF 250 Kbps, Serial up to 1 Mbps	
INDOOR/URBAN RANGE	200 ft (60 m)	300 ft (90 m)
OUTDOOR/RF LINE-OF-SIGHT RANGE	4000 ft (1200 m)	2 miles (3200 m)
TRANSMIT POWER	3.1 mW (+5 dBm) / 6.3 mW (+8 dBm) boost mode	63 mW (+18 dBm)
RECEIVER SENSITIVITY (1% PER)	-100 dBm / -102 dBm boost mode	-101 dBm
FEATURES		
SERIAL DATA INTERFACE	UART, SPI	
CONFIGURATION METHOD	API or AT commands, local or over-the-air (OTA)	
FREQUENCY BAND	ISM 2.4 GHz	
FORM FACTOR	Through-Hole, Surface Mount	
HARDWARE	S2C	
INTERFERENCE IMMUNITY	DSSS (Direct Sequence Spread Spectrum)	
ADC INPUTS	(4) 10-bit ADC inputs	
DIGITAL I/O	15	
ANTENNA OPTIONS	Through-Hole: PCB Antenna, U.FL Connector, RPSMA Connector, or Integrated Wire SMT: RF Pad, PCB Antenna, or U.FL Connector	
OPERATING TEMPERATURE	-40° C to +85° C	
DIMENSIONS (L X W X H) AND WEIGHT	Through-Hole: 0.960 x 1.087 in (2.438 x 2.761 cm) SMT: 0.866 x 1.33 x 0.120 in (2.199 x 3.4 x 0.305 cm)	Through-Hole: 0.960 x 1.297 in (2.438 x 3.294 cm) SMT: 0.866 x 1.33 x 0.120 in (2.199 x 3.4 x 0.305 cm)
NETWORKING AND SECURITY		
PROTOCOL	ZigBee PRO 2007, HA-Ready with support for binding/multicasting	
UPDATABLE TO DIGIMESH PROTOCOL	Yes	
UPDATABLE TO ZIGBEE PROTOCOL	Yes	
ENCRYPTION	128-bit AES	
RELIABLE PACKET DELIVERY	Retries/Acknowledgements	
IDS	PAN ID and addresses, cluster IDs and endpoints (optional)	
CHANNELS	16 channels	15 channels
POWER REQUIREMENTS		
SUPPLY VOLTAGE	2.1 to 3.6V	2.7 to 3.6V
TRANSMIT CURRENT	33 mA @ 3.3 VDC / 45 mA boost mode	120 mA @ 3.3 VDC
RECEIVE CURRENT	28 mA @ 3.3 VDC / 31 mA boost mode	31 mA @ 3.3 VDC
POWER-DOWN CURRENT	<1 µA @ 25° C	<1 µA @ 25° C
REGULATORY APPROVALS		
FCC, IC (NORTH AMERICA)	Yes	Yes
ETSI (EUROPE)	Yes	No
RCM (AUSTRALIA AND NEW ZEALAND)	No (Coming soon)	No (Coming soon)
TELEC (JAPAN)	No (Coming soon)	No

SPECIFICATIONS	Legacy XBee® S1 802.15.4	Legacy XBee-PRO® S1 802.15.4
PERFORMANCE		
RF DATA RATE	250 kbps	250 kbps
INDOR/URBAN RANGE	100 ft (30 m)	300 ft (100 m)
OUTDOOR/RF LINE-OF-SIGHT RANGE	300 ft (100 m)	1 mi (1.6 km)
TRANSMIT POWER	1 mW (+0 dBm)	60 mW (+18 dBm)*
RECEIVER SENSITIVITY (1% PER)	-92 dBm	-100 dBm
DIGI HARDWARE	S1	
TRANSCEIVER CHIPSET	Freescale MC13212	
FEATURES		
SERIAL DATA INTERFACE	3.3V CMOS UART	
CONFIGURATION METHOD	API or AT Commands, local or over-the-air	
FREQUENCY BAND	2.4 GHz	
INTERFERENCE IMMUNITY	DSSS (Direct Sequence Spread Spectrum)	
SERIAL DATA RATE	1200 bps - 250 kbps	
ADC INPUTS	(6) 10-bit ADC inputs	
DIGITAL I/O	8	
ANTENNA OPTIONS	Chip, Wire Whip, U.FL, & RPSMA	
NETWORKING & SECURITY		
ENCRYPTION	128-bit AES	
RELIABLE PACKET DELIVERY	Retries/Acknowledgments	
IDS AND CHANNELS	PAN ID, 64-bit IEEE MAC, 16 Channels	
POWER REQUIREMENTS		
SUPPLY VOLTAGE	2.8 - 3.4VDC	2.8 - 3.4VDC
TRANSMIT CURRENT	45 mA @ 3.3VDC	215 mA @ 3.3VDC
RECEIVE CURRENT	50 mA @ 3.3VDC	55 mA @ 3.3VDC
POWER-DOWN CURRENT	<10 uA @ 25° C	
REGULATORY APPROVALS		
FCC (USA)	OUR-XBEE	OUR-XBEEPRO
IC (CANADA)	4214A-XBEE	4214A-XBEEPRO
ETSI (EUROPE)	Yes	Yes - Max TX 10 mW
C-TICK AUSTRALIA	Yes	
TELEC (JAPAN)	Yes	

It's the easy and fast way to build a wireless sensor network using Digi's XBee modules. To learn more visit docs.digi.com.

877-912-3444 | 952-912-3444

91003137
B2/416